



# 100% Material Declaration Data Sheet CSG484

PK231 (v1.0) November 27, 2007

Material Declaration Data Sheet

**Average Weight: 1.3302 g**

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
<b>Silicon Die</b>					<b>0.0724</b>	<b>5.44%</b>
	Silicon	7440-21-3	100.00		0.0724	
<b>Die Attach</b>					<b>0.0073</b>	<b>0.55%</b>
	Resin		22.00		0.0016	
	Silver	7440-22-4	78.00		0.0057	
<b>Mold Compound</b>					<b>0.4473</b>	<b>33.62%</b>
	Resin	N/A	12.00		0.0537	
	SiO2	60676-86-0	88.00		0.3936	
<b>Laminate</b>					<b>0.5963</b>	<b>44.83%</b>
	Laminate	N/A			0.3159	
	Solder Mask	N/A			0.0346	
	Copper	7440-50-8		Metal Layer	0.2309	
	Nickel	7440-02-0		Metal Layer	0.0126	
	Gold	7440-57-5		Metal Layer	0.0023	
<b>Wire</b>					<b>0.0122</b>	<b>0.92%</b>
	Gold	7440-57-5		Metal Layer	0.0122	
<b>Solder Balls</b>					<b>0.2303</b>	<b>14.64%</b>
	Tin	7440-31-5	95.50		0.1859	
	Silver	7440-22-4	4.00		0.0078	
	Copper	7440-50-8	0.50		0.0010	

## Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
11/27/07	1.0	Initial release.